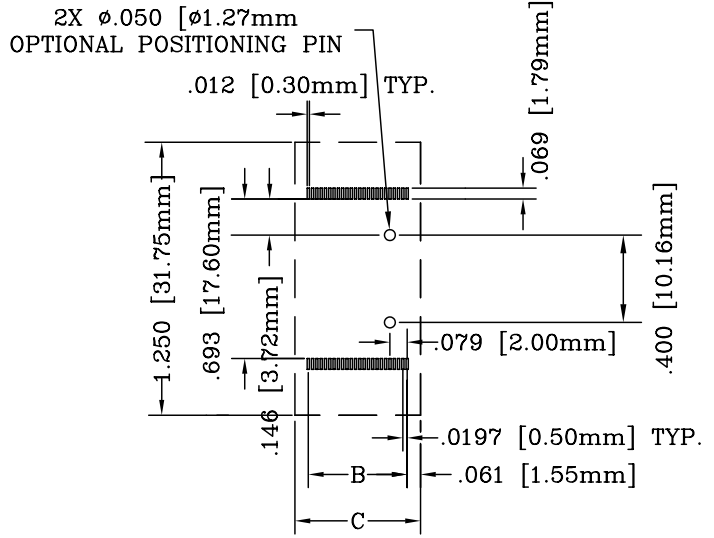


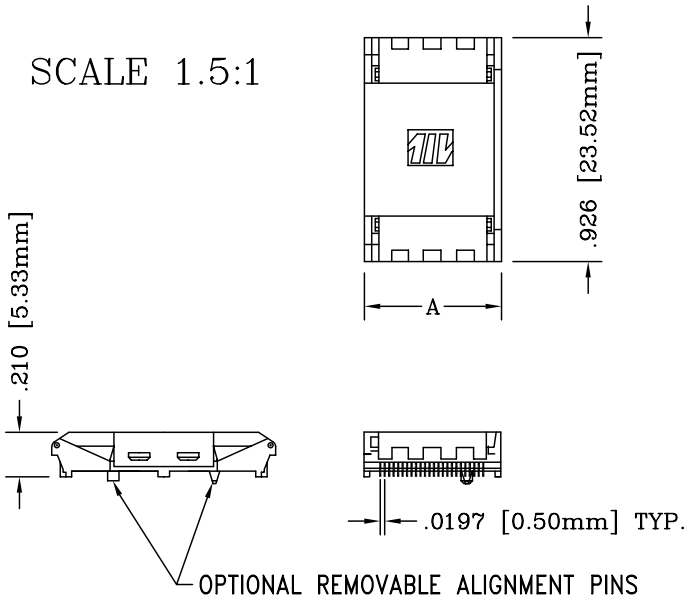
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	06/09/05	H.N.

SKT2322

SOCKET LAND-PAD FOOTPRINT



SCALE 1.5:1



NO LEAD

SPECIFICATIONS:

- FOR OEM, PROGRAMMING, PROTOTYPING AND TEST APPLICATIONS
- SURFACE MOUNT ZERO-INSERTION FORCE
- LAND-PAD FOOTPRINT COMMON FOR PACKAGE AND SOCKET
- EFFORTLESS PACKAGE LOADING AND UNLOADING
- BODY, LID AND LOCK MATERIAL: LCP
- TERMINAL MATERIAL: COPPER ALLOY, WITH PALLADIUM OVER NICKEL PLATING
- MINIMUM INSERTION/WITHDRAWAL CYCLES: 50
- TEMPERATURE RANGE: -55°C TO + 105°C
- CURRENT RATING: 0.5 AMP
- FLAMMABILITY: 940V-0
- VERY POSITIVE LOCKING LID DESIGN

PACKAGE SPECIFICATIONS	
PIN COUNT	≡ 48
LEAD PITCH	≡ 0.50mm
PACKAGE WIDTH	≡ 18.40mm

ET PACKAGE CODE	DIM A		DIM B		DIM C	
	mm	inches	mm	inches	mm	inches
48-TS01	13.85	.545	11.50	.453	15.62	.615

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

		Emulation Technology, Inc. — VLSI and SMT ADAPTERS and ACCESSORIES —	
		2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051 TEL:(408)982-0660 FAX:(408)982-0664	
SHEET: 1 OF 1	DATE: 06/09/05	REVISION: A	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-TSO-SM-048-B	DESCRIPTION: S-TSO-SM-048-B
Scale 1:1	DO NOT SCALE DRAWING		